

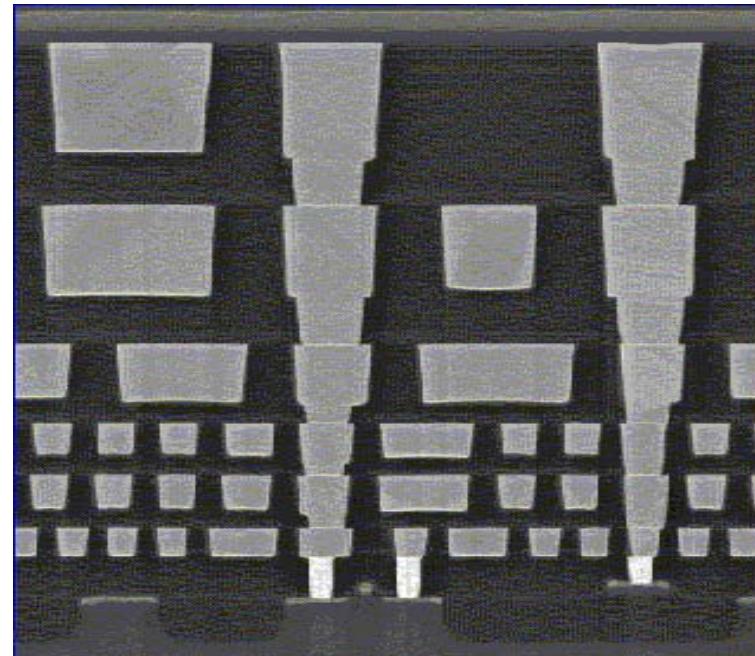
# **Issues in VLSI interconnect**

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Technion – Israel Institute of Technology

February 2004

# In nanometer CMOS Interconnect becomes critical

- Interconnect can dominate
  - **Timing**
  - **Power**
  - **Noise**
  - **Layout density**
  - **Design effort**

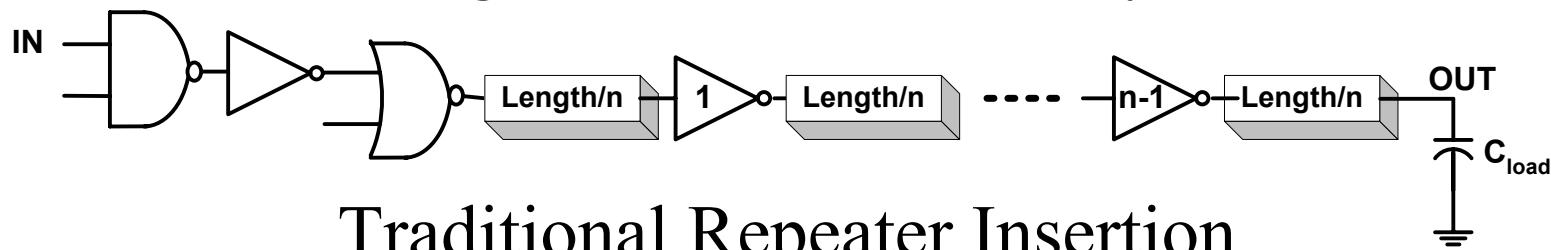


0.13  $\mu\text{m}$  cross-section, source - Intel

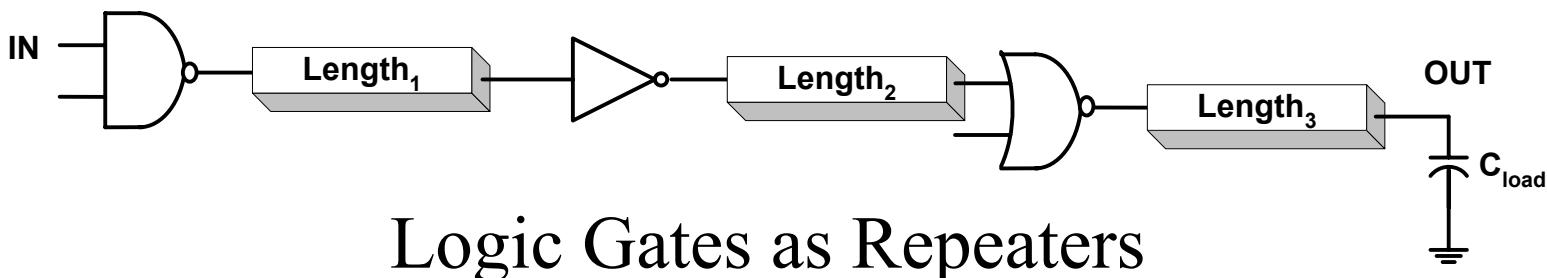
# Logic Gates as Repeaters (LGR)



Long wire dominates delay



Traditional Repeater Insertion



Logic Gates as Repeaters

- + *Timing improvement similar to traditional Repeater Insertion*
- + *No additional devices – area and power efficient*

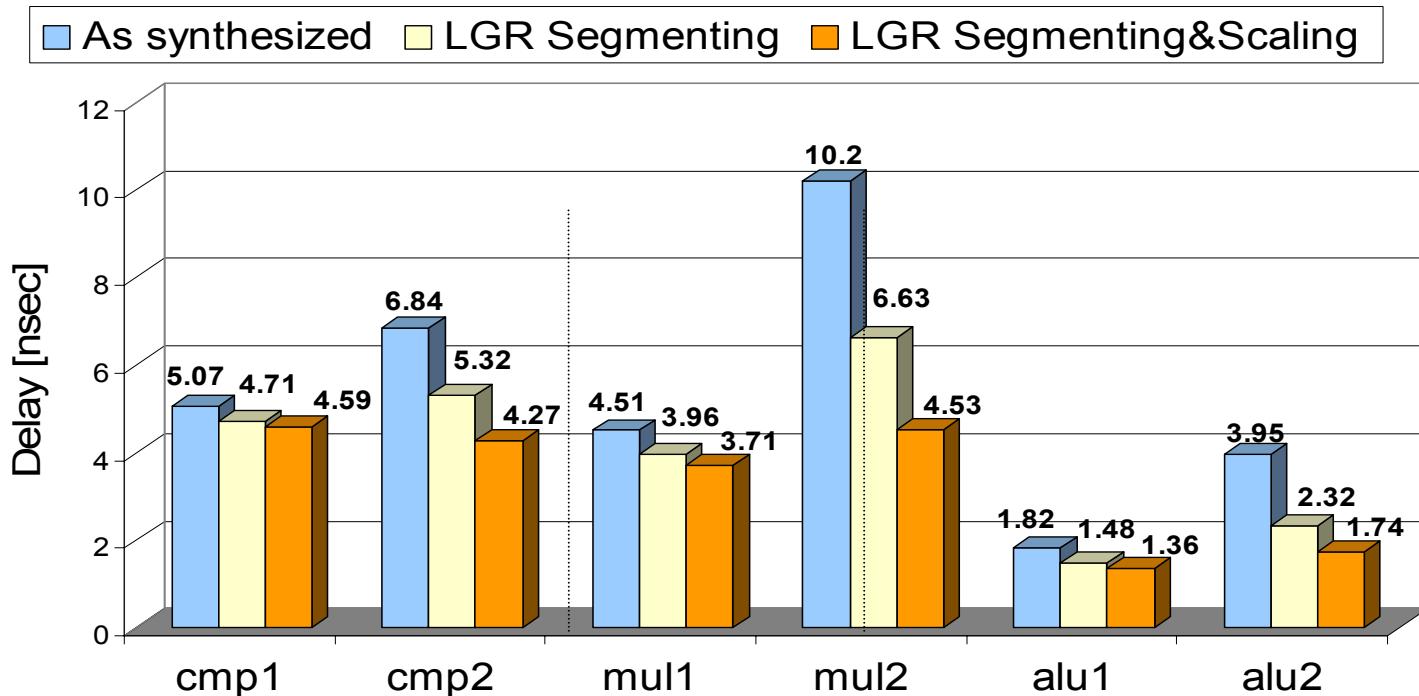


# LGR in Physical Synthesis

**Stage 1:** Test circuits Implementation using commercial tools

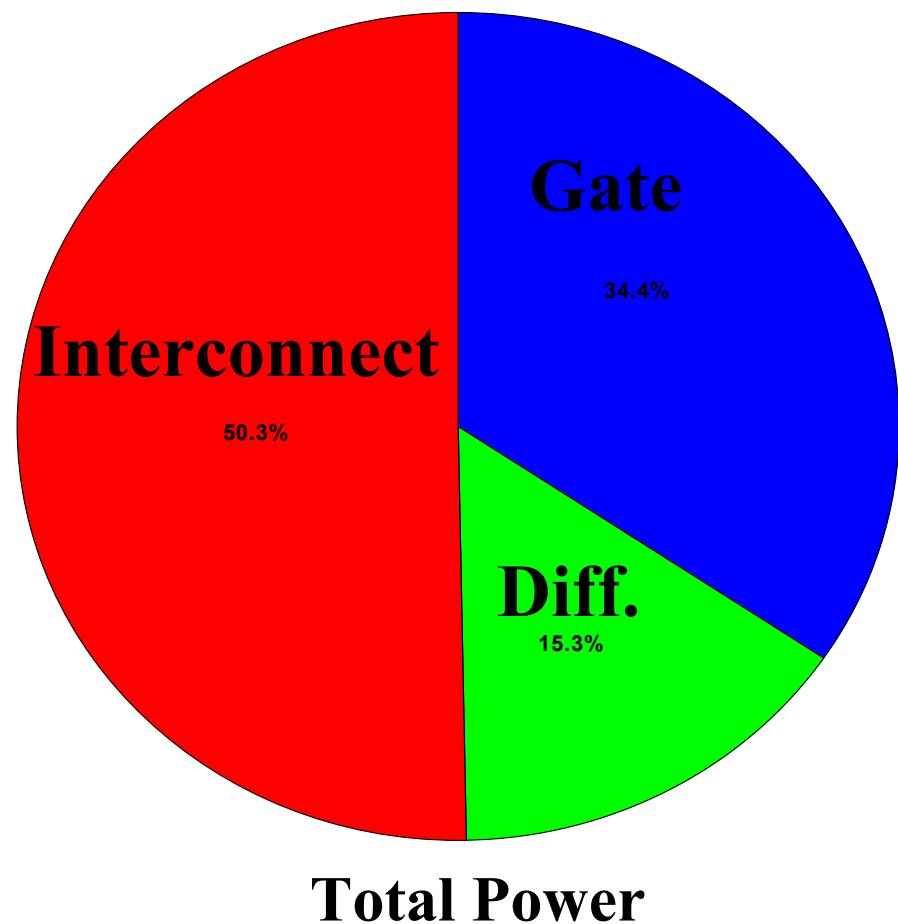
**Stage 2:** Post-Layout extraction of critical path

**Stage 3:** LGR optimization of critical path

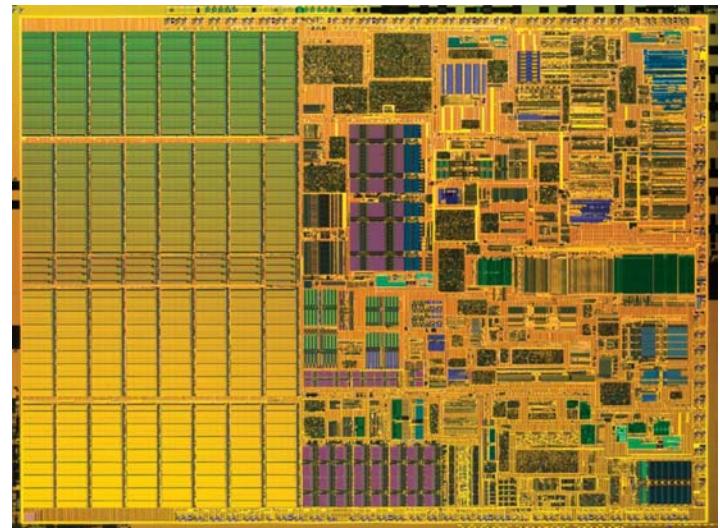


- \* A. Morgenshtein, M. Moreinis, I. Wagner and A. Kolodny,  
“Logic gates as Repeaters”, IFIP VLSI-SoC , December 2003.

# Dynamic Power Dissipation in a microprocessor



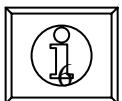
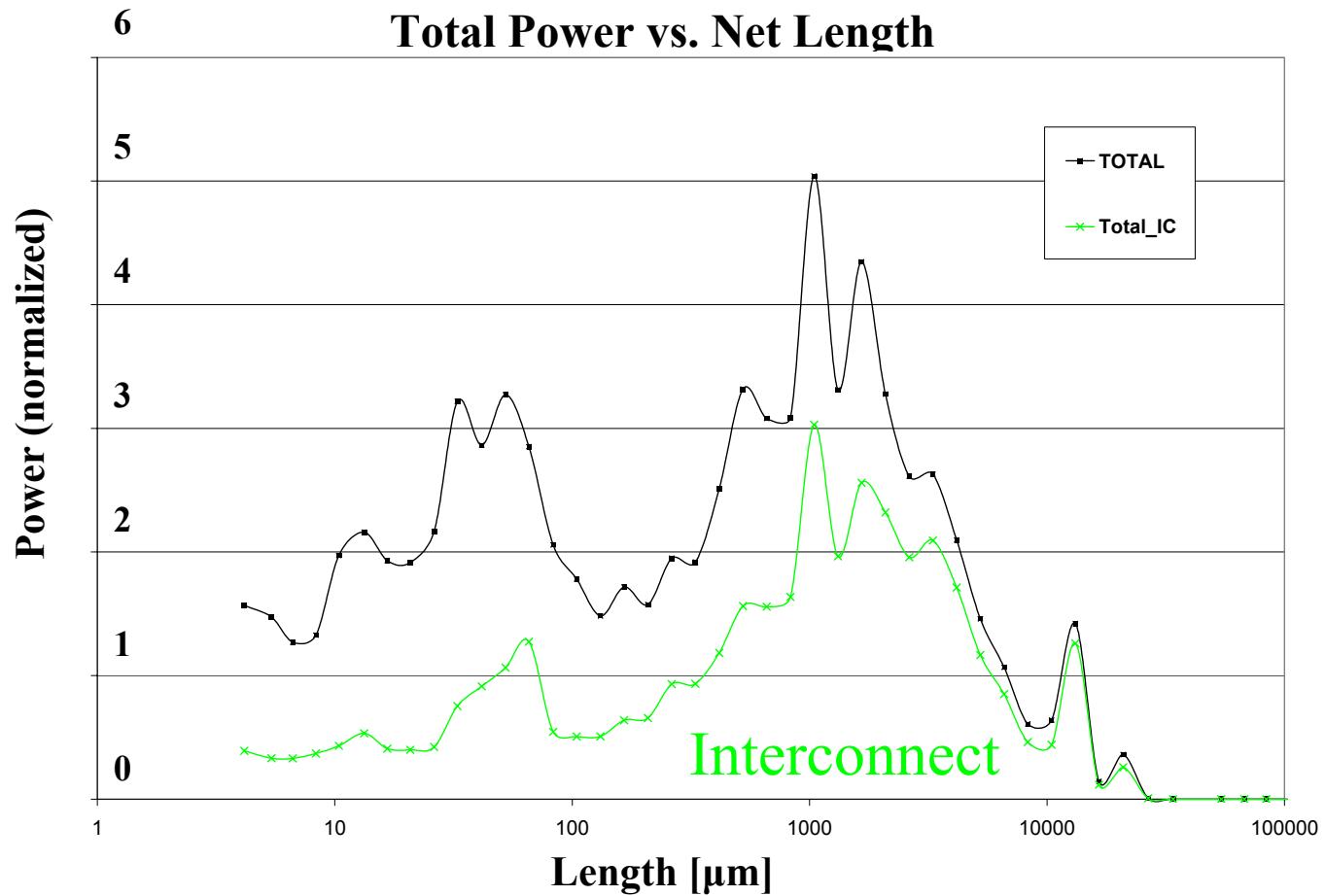
- 0.13 $\mu$ m CMOS
- 77 million transistors
- Die size: 88 mm<sup>2</sup>



\* N. Magen, A. Kolodny, U. Weiser and N. Shamir, "Interconnect-Related Energy dissipation in a Low-Power Microprocessor", Proc. International System Level Interconnect Prediction workshop (SLIP) , February 2004.

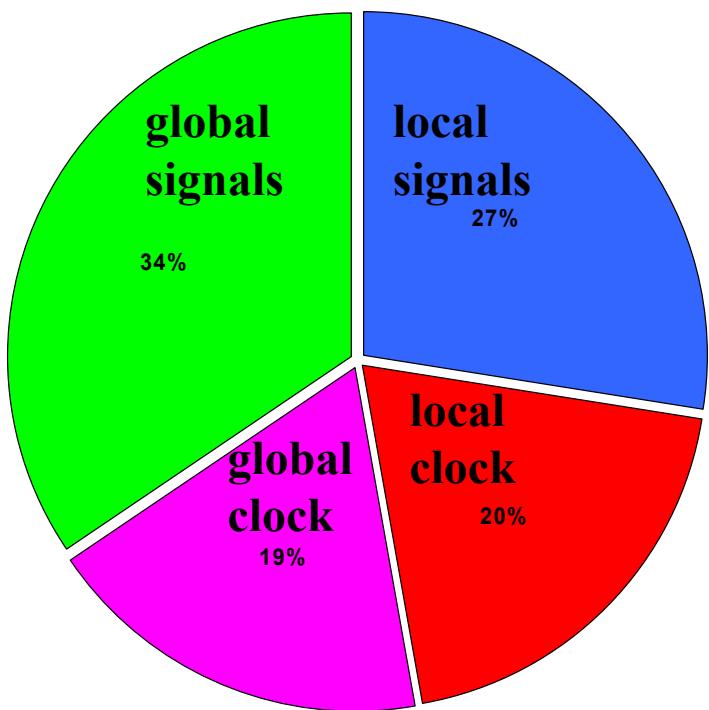
# Power Distribution by Wirelength

- Total Dynamic Power
- Global clock – not included
- Local signals nets = 66%
- Global signals nets = 34%

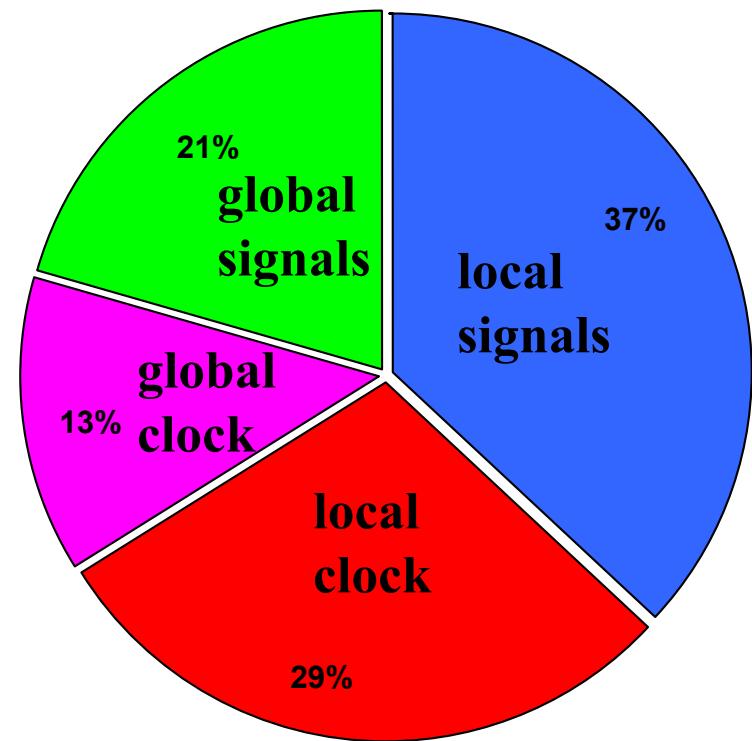


# Power in local and global signals

- Interconnect consumes 50% of total dynamic power
- Clock power ~40% (of Interconnect and total)
- 90% of power consumed by 10% of nets
- Interconnect design is NOT power-aware !

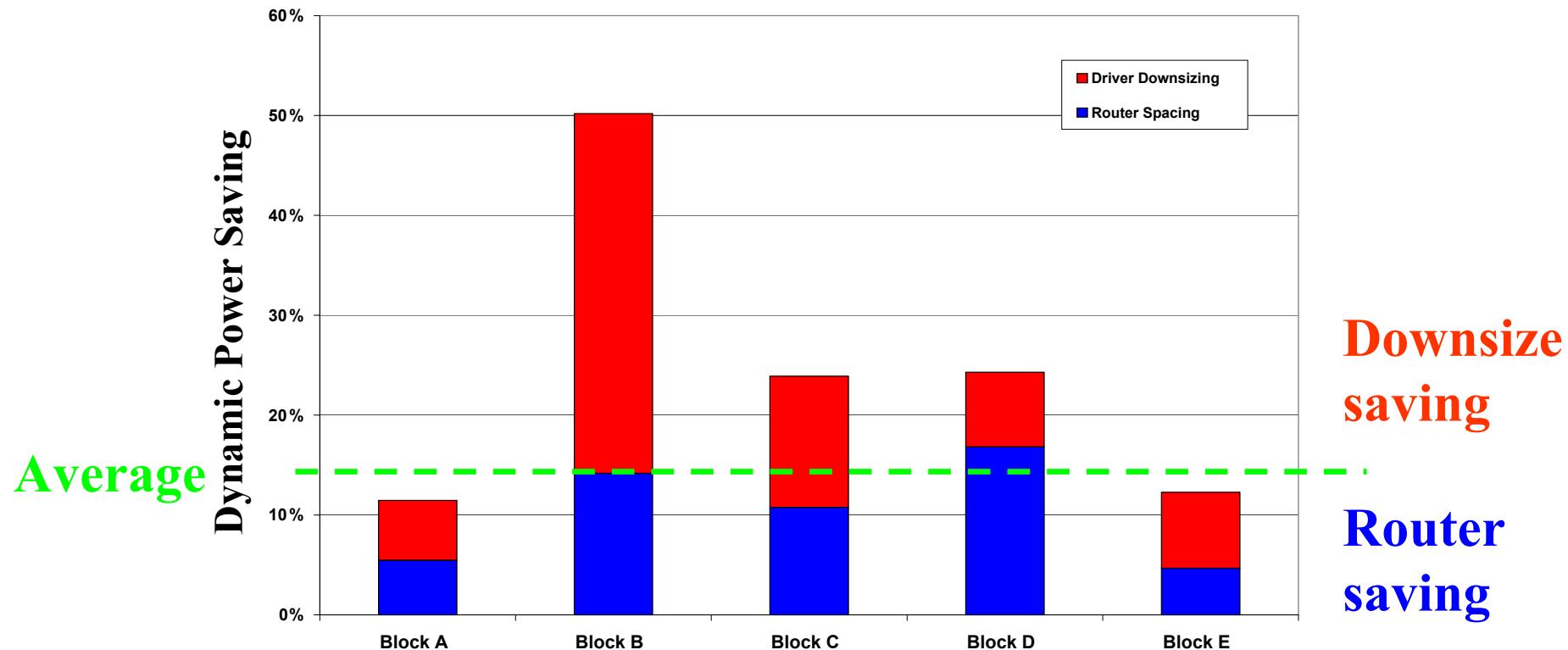


**Interconnect power**  
(Interconnect only)



**Total dynamic power**  
(Gate, Diffusion and Interconnect)

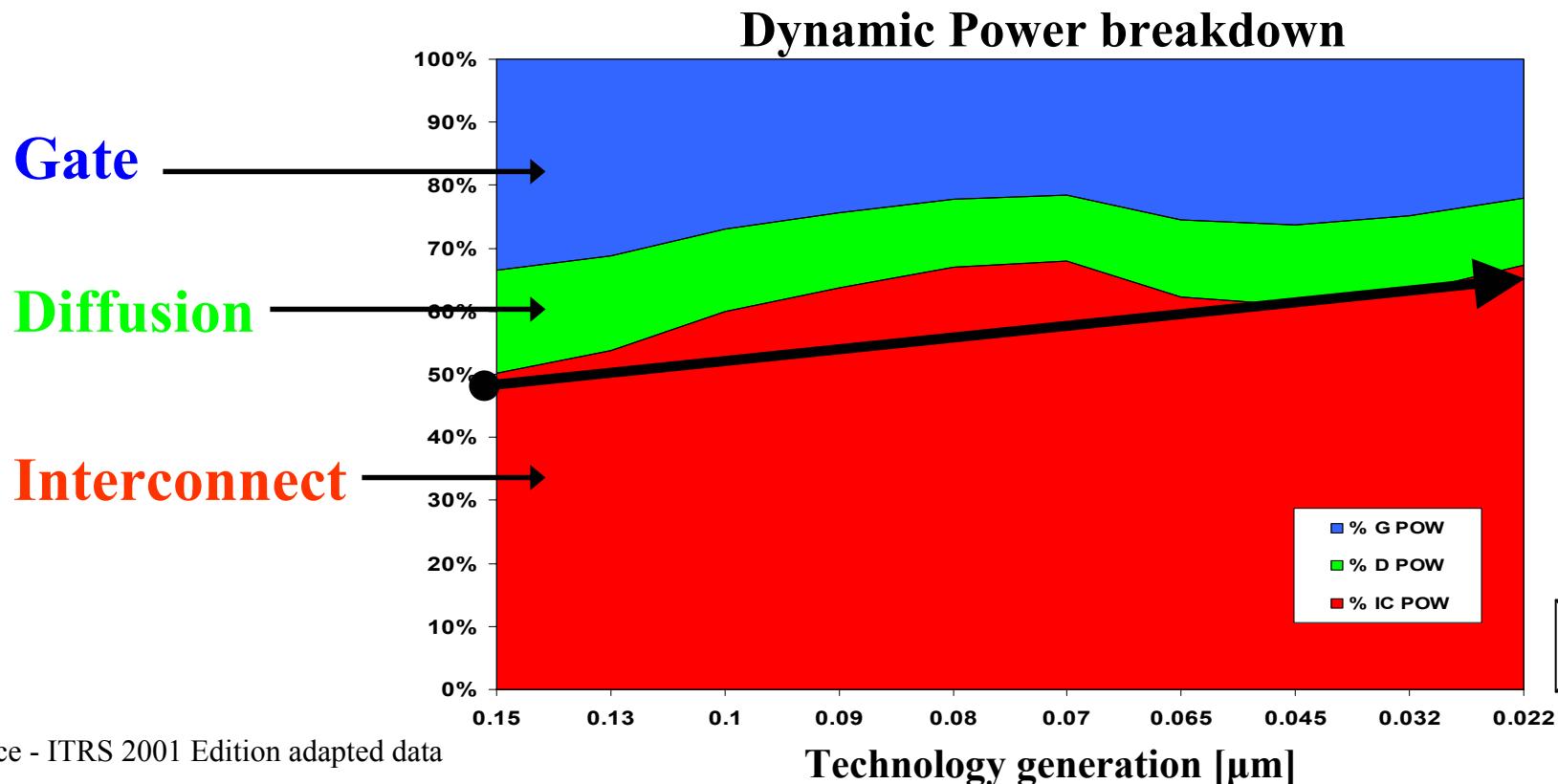
# Savings by power-aware router



Average saving results: 14.3% for ASIC blocks <sup>1</sup>

1 - Estimated based on clock interconnect power

# Future of Interconnect Power



Interconnect power grows to 65%-80% within 5 years !





# Networks-on-Chip (NoC)

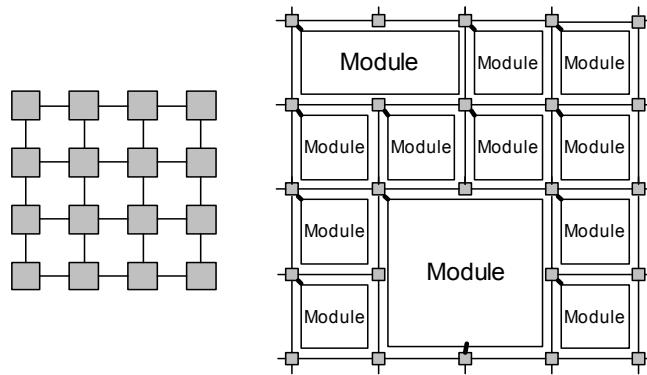
**Faculty:** Israel Cidon, Ran Ginosar, Avinoam Kolody

**Students:** Evgeny Bolotin, Walter Isaskhar

Arkadiy Morgenshtein, Reuven Dobkin

# Why SoC needs NoC?

- Scalability
  - Traditional chip interconnections are not scalable
- Optimized NoC links
  - Interconnect dominates delay, noise and power in nanometer technologies
- Synchronization
  - Delay of global wire longer than a clock cycle
  - GALS Systems
- Modularity and reuse
  - SoC design productivity

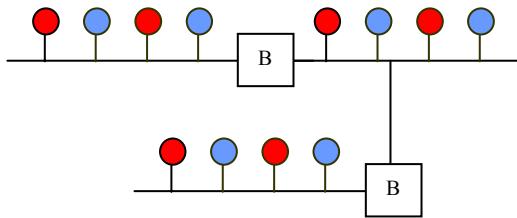


**Goal: Cost-effective network that satisfies on-chip QoS requirements**

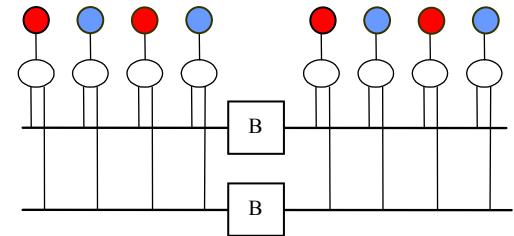


# Traditional Solution-Bus

Segmented Bus



Multi-Level  
Segmented  
Bus



## Original bus features:

- One transaction at a time
- Central Arbiter
- Limited bandwidth
- Synchronous
- Low cost

**Is it still?**

## New features:

- Versatile bus architectures
- Pipelining capability
- Burst transfer
- Split transactions
- Transaction preemption and resume
- Transaction reordering...



# NoC Cost Scalability vs. Alternative Solutions

<i>Arch</i>	<i>Total Area</i>	<i>Power Dissipation</i>	<i>Operating Frequency</i>
<i>NS-Bus</i>	$O(n^3\sqrt{n})$	$O(n\sqrt{n})$	$O\left(\frac{1}{n^2}\right)$
<i>S-Bus</i>	$O(n^2\sqrt{n})$	$O(n\sqrt{n})$	$O\left(\frac{1}{n}\right)$
<i>NoC</i>	$O(n)$	$O(n)$	$O(1)$
<i>PTP</i>	$O(n^2\sqrt{n})$	$O(n\sqrt{n})$	$O\left(\frac{1}{n}\right)$

- \* E. Bolotin, I. Cidon, R. Ginosar and A. Kolodny, “Cost Considerations in Network-on-Chip”, INTEGRATION – the VLSI journal, 2003)

# Solution – Network on Chip

Networks are preferred over buses:

- Scalability
- Higher bandwidth
- Concurrency, effective spatial reuse of resources
- Higher levels of abstraction
- Modularity - Design Productivity Improvement



# Network on Chip Requirements

- Different QoS must be supported
  - Bandwidth
  - Latency
- Distributed deadlock free routing
- Distributed congestion/flow control
- Low VLSI Cost



# QNoC: QoS NoC

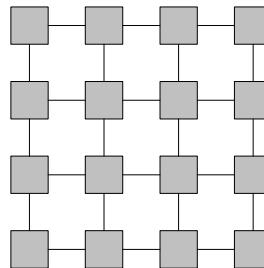
Define Service Levels (SLs):

- *Signaling*
  - *Real-Time*
  - *Read/Write (RD/WR)*
  - *Block-Transfer*
- ✓ Different QoS for each SL

\* E. Bolotin, I. Cidon, R. Ginosar and A. Kolodny., “QNoC: QoS architecture and design process for Network on Chip”, JSA special issue on NOC, December 2003

# QNoC Architecture

- Mesh Topology



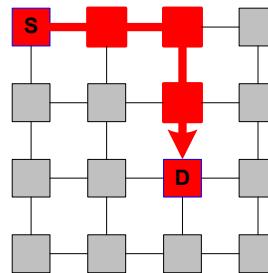
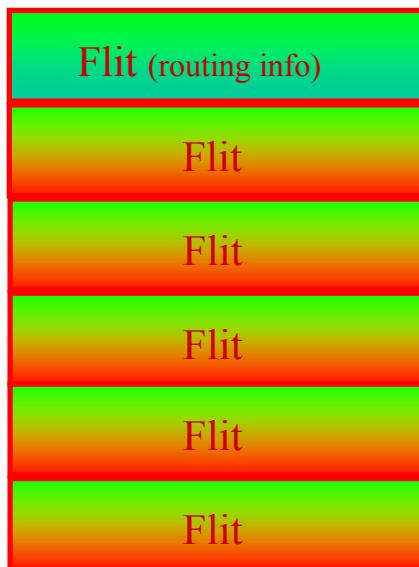
- Fixed shortest path routing (X-Y)
  - ✓ Simple Router (no tables, simple logic)
  - ✓ Power efficient communication
  - ✓ No deadlock scenario



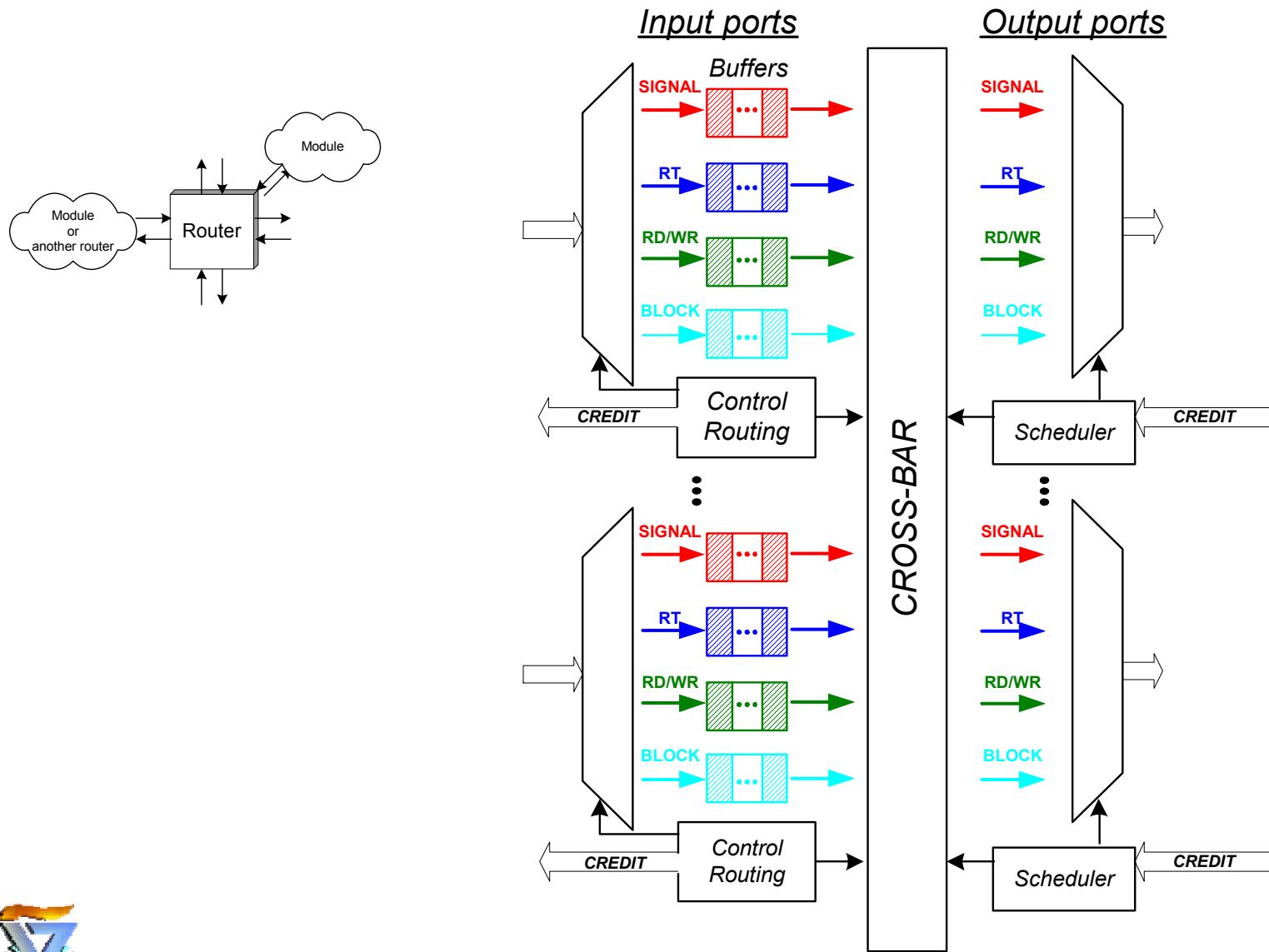
# QNoC Architecture

- Wormhole Routing
  - ✓ For reduced buffering

Wormhole Packet:



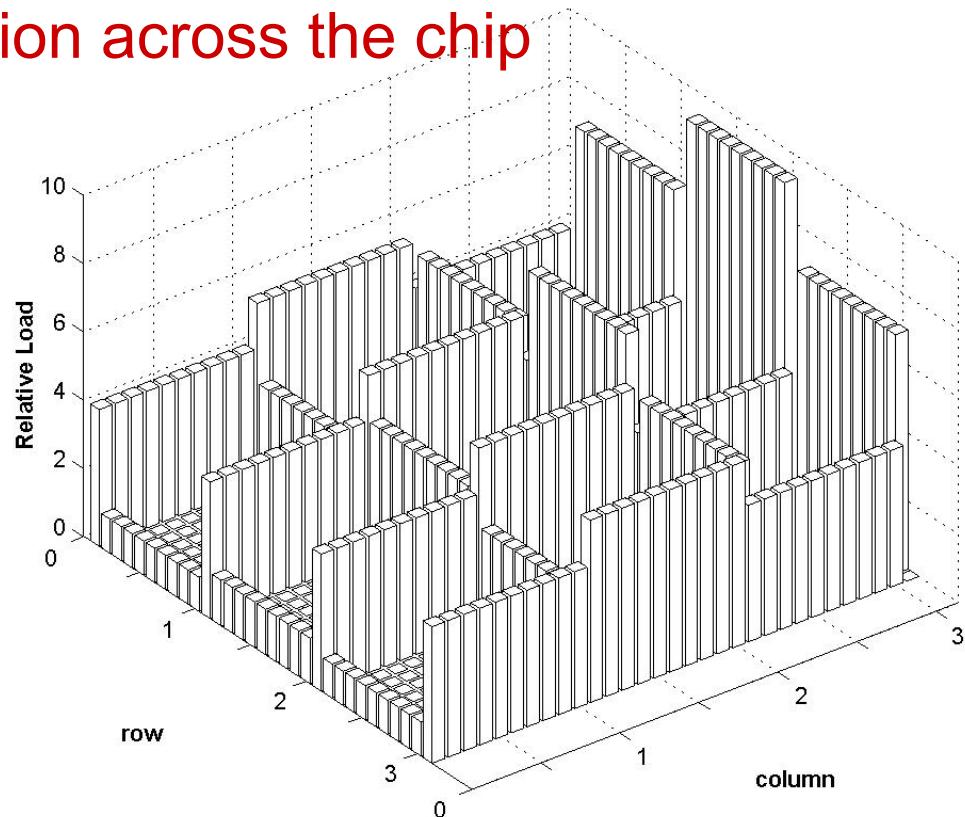
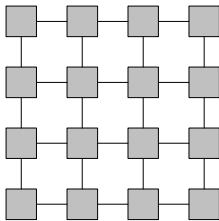
# QNoC Wormhole Router



# QNoC Design Process - Optimization

- Trim Unnecessary Resources
- Adjust each link capacity according to its load
  - ✓ Equal link utilization across the chip

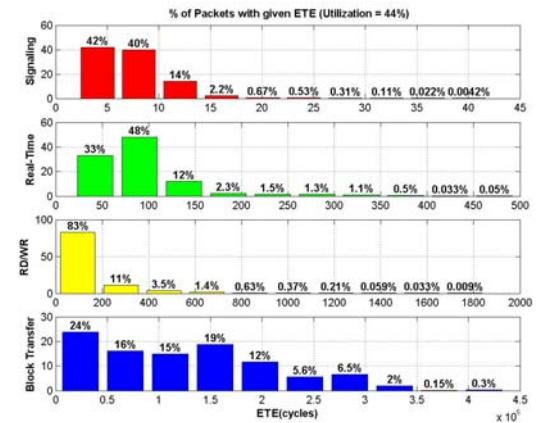
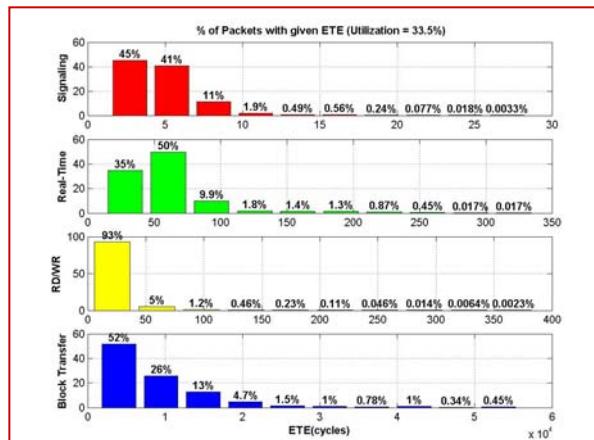
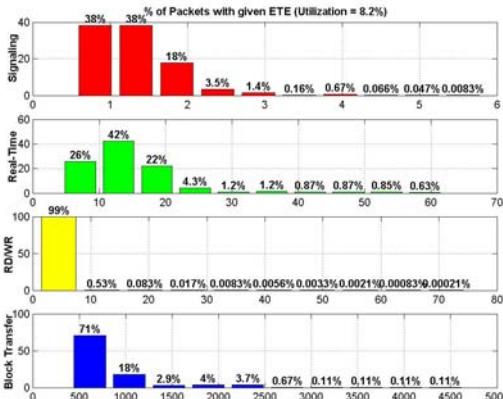
Example: (Uniform mesh)



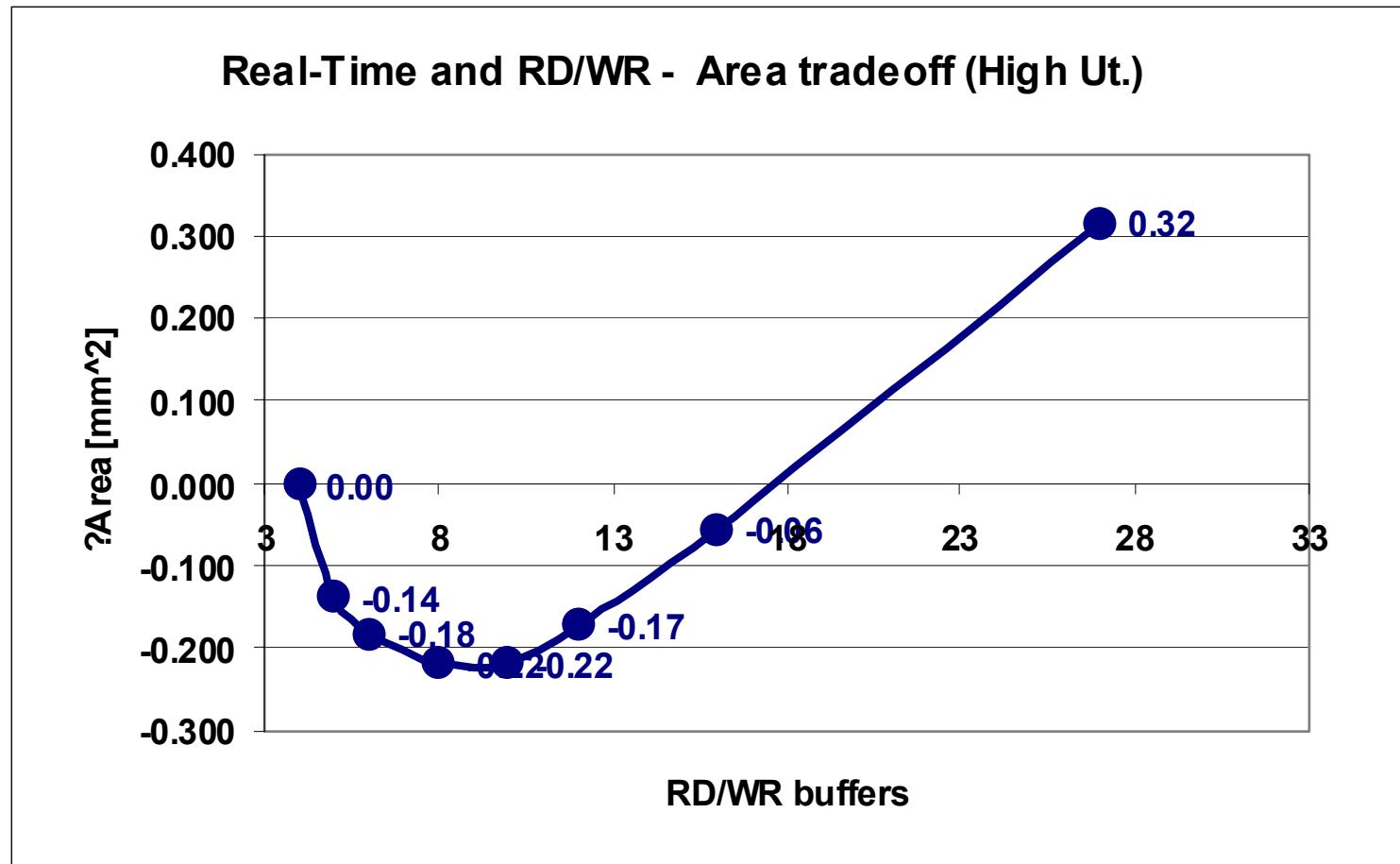
# Non-Uniform Traffic - Observations

Various network BW allocations were tried in order to reach desired QoS requirements:

Allocated Link BW [Gbps]	Average Link Utilization [%]	Packet ETE delay of packets [ns or cycles]			
		Signaling (99.9%)	Real-Time (99.9%)	RD/WR (99%)	Block-Transfer (99%)
2752Gbps	8.2	5ns	60ns	20ns	4.5 $\mu$ s
1376Gbps	16.5	10ns	120ns	50ns	13 $\mu$ s
688Gbps	33.5	20ns	270ns	120ns	45 $\mu$ s
459Gbps	44	35ns	400ns	1.3 $\mu$ s	350 $\mu$ s



# Cost tradeoffs



- \* E. Bolotin, I. Cidon, R. Ginosar and A. Kolodny, “Cost Considerations in Network-on-Chip”, INTEGRATION – the VLSI journal, 2003)

# Future Directions

- Module placement
- Link Optimization
- Interfaces
- Physical design
- Error correction
- Synchronization
- NoC for reconfigurable chips
- Design and validation methods
- .....

